

Abstract

The present invention provides a bonding device, a bonding method and a computer-readable storage medium. The bonding device comprises a chip picking assembly and a chip bonding assembly. The chip picking assembly comprises a first body and a first rotating motor. The first body is provided with a plurality of picking heads. First suction surfaces for chips of the plurality of picking heads are located on a same plane, and facing a same first direction. The first rotating motor is connected to the first body, for rotating and switching the plurality of picking heads one by one to a preset picking station, to pick up corresponding chips one by one. The chip bonding assembly is located in the first direction of the chip picking assembly, and comprising a second body. The second body is provided with a plurality of bonding heads. Second suction surfaces for chips of the plurality of bonding heads are located on a same plane, and facing a second direction where the chip picking assembly is located, to simultaneously obtain the corresponding chips from the first suction surfaces of the plurality of picking heads.

(FIG. 4)